

Low Capacitance TVS Diode Array

APPLICATIONS

- ◆ Cell Phone Handsets and Accessories
- ◆ Microprocessor based equipment
- ◆ Personal Digital Assistants (PDA's)
- ◆ Notebooks, Desktops, and Servers
- ◆ Portable Instrumentation
- ◆ Peripherals
- ◆ USB Interface

IEC COMPATIBILITY

- ◆ IEC61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50 η s)
- ◆ IEC61000-4-5 (Lightning) 12A (8/20 μ s)

FEATURES

- ◆ 350 Watts Peak Pulse Power per Line ($t_p=8/20\mu\text{s}$)
- ◆ Protects one I/O line (bidirectional)
- ◆ Low clamping voltage
- ◆ Working voltages: 3V, 5V, 8V, 12V, 15V, 24V
- ◆ Low leakage current

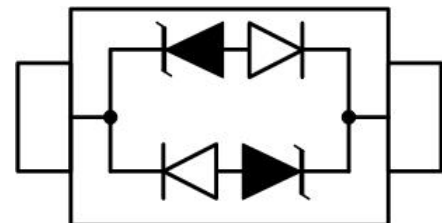
MECHANICAL CHARACTERISTICS

- ◆ JEDEC SOD-323 Package
- ◆ Molding Compound Flammability Rating : UL 94V-0
- ◆ Weight 5 Milligrams (Approximate)
- ◆ Quantity Per Reel : 3,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free

SOD-323



PIN CONFIGURATION

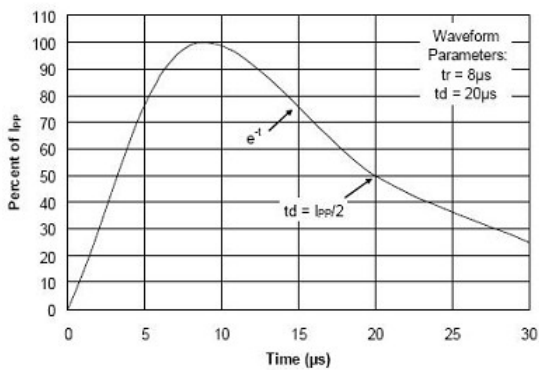


DEVICE CHARACTERISTICS

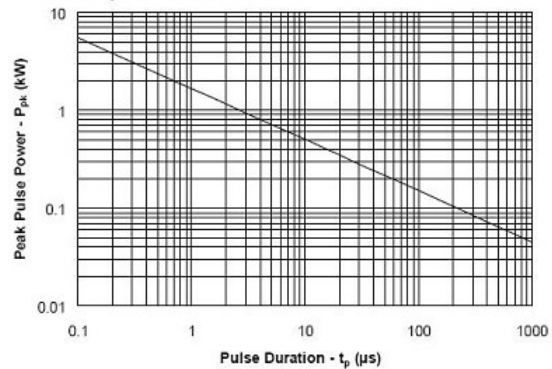
MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20µs waveform)	P _{PP}	350	Watts
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)									
PART NUMBER	DEVICE MARKING	V _{RWM}	V _B	I _T	V _C	V _C		I _R	C _T
		(V) (max.)	(V) (min.)	(mA)	@1A (max.)	(max.)	(@A)	(µA) (max.)	(pF) (typ.)
LC03CI	CC	3.0	4.0	1	5.15	13.9	8	20	0.4
LC05CI	AC	5.0	6.0	1	9.80	18.3	8	5	0.4
LC08CI	BC	8.0	8.5	1	13.40	18.5	8	2	0.4
LC12CI	DC	12.0	13.3	1	19.00	28.6	6	1	0.4
LC15CI	EC	15.0	16.7	1	24.00	31.8	5	1	0.4
LC24CI	HC	24.0	26.7	1	43.00	56.0	3	1	0.4

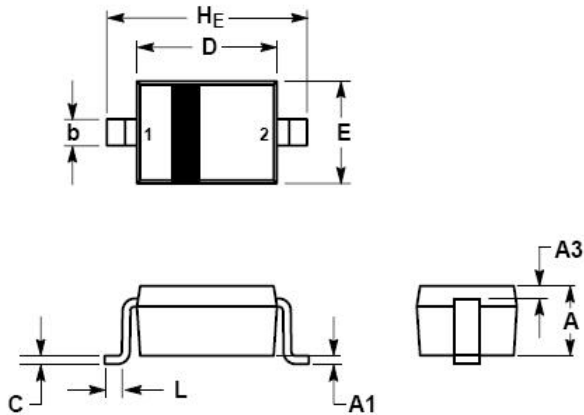
Pulse Waveform



Non-Repetitive Peak Pulse Power vs. Pulse Time



SOD-323 PACKAGE OUTLINE & DIMENSIONS



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H_E	2.30	2.50	2.70	0.090	0.098	0.105

*** SOLDERING FOOTPRINT**

